Bill of Material for TIDA-00262
On 7/25/2014

Comment	Pattern	Quantity	Components	
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	0402L	1	R13	RES, 4.75k ohm, 1%, 0.063W, 0402
2.2µH	0805_HV	1	L2	Inductor, Multilayer, Ferrite, 2.2uH, 0.6A, 0.34 ohm, SMD
59S10H-40ML5-Y	59S10H-40ML5-Y	1	CN1	Straight Plug PCB
AR0140AT3C00XUEA0	iBGA_9x9_63	1	U4	1/4-Inch Digital Image Sensor, iBGA_9x9_63
BLM18KG601SN1D	603	3	L1, L6, L7	1.3A Ferrite Bead, 600 ohm @ 100MHz, SMD
C1005X7R1E104K050BB	0402L	6	C2, C8, C13, C23, C29, C32	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0402
C1005X7R1H104K	0402L	2	C7, C15	CAP, CERM, 0.1uF, 50V, +/-10%, C0G/NP0, 0402
CGA4J1X7R1E475M125AC	0805L	1	C1	CAP, CERM, 4.7uF, 25V, +/-20%, X7R, 0805
CIG21L4R7MNE	0805_HV	1	L4	Inductor, Shielded, Composite, 4.7uH, 0.75A, 0.26 ohm, SMD
CL05B105KQ5NQNC	402	1	C28	CAP CER 1UF 6.3V 10% X7R 0402
CL10B475KQ8NQNC	603	3	C4, C10, Cout2	CAP CER 4.7UF 6.3V 10% X7R 0603
CL21B106KOQNNNE	805	1	Cin1	CAP CER 10UF 16V 10% X7R 0805
CMT821	CMT821	1	LH1	Sunex Lens Holder
CRCW04020000Z0ED	0402L	9	R12, R55, R66, R77, R mode, 1Rtest1, Rtest2, Rvdd, Rvddio	RES, 0 ohm, 5%, 0.063W, 0402
CRCW0402100KFKED	0402L	1	Rfbb	RES, 100k ohm, 1%, 0.063W, 0402
CRCW040210K0JNED	0402L	5	R7, R8, R9, R98, R99	RES, 10k ohm, 5%, 0.063W, 0402
CRCW040210R0JNED	0402L	1	R15	RES, 10 ohm, 5%, 0.063W, 0402
CRCW04021R00JNED	0402L	1	R14	RES, 1.0 ohm, 5%, 0.063W, 0402
CRCW0402261KFKED	0402L	1	Rfbt	RES, 261k ohm, 1%, 0.063W, 0402
CRCW04022R00JNED	0402L	1	R11	RES, 2.0 ohm, 5%, 0.063W, 0402
CRCW040233R0JNED	0402L	1	R6	RES, 33 ohm, 5%, 0.063W, 0402
CRCW04023K30JNED	0402L	2	Rpu1, Rpu2	RES, 3.3k ohm, 5%, 0.063W, 0402
CRCW040249R9FKED	0402L	1	R5	RES, 49.9 ohm, 1%, 0.063W, 0402
CRCW04025R10JNED	0402L	1	R16	RES, 5.1 ohm, 5%, 0.063W, 0402
CRCW06031K00JNEA	0603L	2	R1, R2	RES, 1.0k ohm, 5%, 0.1W, 0603
DS90UB913ATRTVTQ1	RTV0032A	1	U3	DS90UB913A-Q1/DS90UB914A-Q1 25 to 100 MHz 10/20-Bit FPD-Link III Serializer and Deserializer, RTV0032A
ECS-2018-480-BN	ECS_2018	1	Y1	XO, 48.000MHz, 1.8V, SMD
Fiducial	Fiducial10-20	6	FID1, FID2, FID3, FID4, FID5, FID6	Fiducial mark. There is nothing to buy or mount.
GRM155R71C103KA01D	0402L	9	C6, C9, C12, C14, C18, C20, C22, C24, C30	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0402
GRM155R71C104KA88D	0402L	6	C5, C11, C17, C19, C21, C27	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402
GRM188R71A225KE15D	0603L	2	Cin2, Cin3	CAP, CERM, 2.2uF, 10V, +/-10%, X7R, 0603
GRM21BR71A106KE51L	0805_HV	1	C26	CAP, CERM, 10uF, 10V, +/-10%, X7R, 0805
GRM21BR71A106KE51L	0805L	1	C31	CAP, CERM, 10uF, 10V, +/-10%, X7R, 0805
GRM31CR71A226KE15L	1206L	2	C16, Cout1	CAP, CERM, 22uF, 10V, +/-10%, X7R, 1206
LQM21PN2R2MC0D	0805_HV	1	L3	Inductor, Multilayer, Ferrite, 2.2uH, 0.6A, 0.34 ohm, SMD
NLCV32T-101K-PF	NLCV32	1	L5	Inductor, Wirewound, Ferrite, 100uH, 0.12A, 3.7 ohm, SMD
Size: 0.65" x 0.20 "	Label_650x200	1	LBL1	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll
TPS3836E18QDBV	DBV0005A_N	1	U5	NANOPOWER SUPERVISORY CIRCUITS, 1.71 V, DBV0005A
TPS62170DSGR	DSG0008A	1	U1	Buck Step Down Regulator with 3 to 17 V Input and 0.9 to 6 V Output, -40 to 85 degC, 8-Pin WSON (DSG), Green (RoHS & no Sb/Br)
TPS62231DRYT	DRY0006A	1	U2	Buck Step Down Regulator with 2.05 to 6 V Input and 1.8 V Output, -40 to 85 degC, 6-Pin SON (DRY), Green (RoHS & no Sb/Br)

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